



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-08-17
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacobello	Representative Title	IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	H2RH*TWU201G	A	ZA41	2015-08-17
Amount	UoM	Unit type	ST ECOPACK Grade	
400.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	260	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used c	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
RAD	26 - 6.05 - 2.95	2	wire	
Comment	Package: DO 15; MDF valid for BZW06-342RL; P6KE400A; P6KE400ARL			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th June 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	H2RH*TWU201G					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon die	Other inorganic materials	1.873	mg	supplier	die	Silicon (Si)	7440-21-3		1.788	mg	954618	4470
Silicon die				supplier	metallization	Aluminium (Al)	7429-90-5		0.041	mg	21890	103
Silicon die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.024	mg	12814	60
Silicon die				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.007	mg	3737	18
Silicon die				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1068	5
Silicon die				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.011	mg	5873	28
Leadframe	Copper & its alloys	281.936	mg	supplier	alloy	Copper (Cu)	7440-50-8		281.795	mg	899500	704488
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.028	mg	99	70
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.028	mg	99	70
Leadframe				supplier	alloy	Phosphorus (P)	12185-10-3		0.085	mg	301	213
Soft solder	Solder	4.799	mg	Supplier	soft solder	Silver (Ag)	7440-22-4		0.24	mg	50010	600
Soft solder				Supplier	soft solder	Tin (Sn)	7440-31-5		0.12	mg	25005	300
Soft solder				JIG R	soft solder	Lead (Pb)	7439-92-1	7a-Lead in high me	4.439	mg	924984	11098
Encapsulation	Other organic material	107.395	mg	Supplier	Molding Compound	silica fused	7631-86-9		42.958	mg	400000	107395
Encapsulation				Supplier	Molding Compound	silica quartz	14808-60-7		61.752	mg	574999	154380
Encapsulation				Supplier	Molding Compound	phenolic resin	9003-35-4		2.148	mg	20001	5370
Encapsulation				Supplier	Molding Compound	carbon black	1333-86-4		0.537	mg	5000	1343
connections coating	Solder	3.997	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		3.997	mg	1000000	9993